Refractive index inhomogeneity of LaF_3 film at deep ultraviolet wavelength

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It is well known that the optical property of an optical thin film can be influenced by even small inhomogeneity of refractive index (RI). In order to investigate the RI inhomogeneity of LaF₃ single layer in deep ultraviolet (DUV) range, single-layer LaF₃ samples deposited on fused silica and CaF₂ substrates are prepared by resistive heating evaporation at different deposition temperatures. The reflectance and transmittance spectra of LaF₃ film samples are measured with a spectrophotometer, and used to calculate the RI inhomogeneity. The experimental results show that no RI inhomogeneity of LaF₃ film is observed when deposited on CaF₂ substrate, while negative RI inhomogeneity is presented when deposited on fused silica substrate. The level of inhomogeneity is affected by the substrate temperature, which decreases with the increasing substrate temperature from 250 to 400 °C.

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It is well known that the transmittance and reflectance spectra of an optical thin film can be influenced by even small inhomogeneity or variation in its complex refractive index (RI) profile^[1]. Inhomogeneous layers can be either helpful or harmful to the optical performance of thin film. If the RI of an inhomogeneous film changes smoothly from the substrate to the ambient medium, it will be good for antireflection coatings. While in many multilayers, inhomogeneous film will be a problem to performance optimization and accurate thickness control^[2]. An existing inhomogeneous model developed by Arndt *et al.*^[3] was used to determine the optical constants from reflectance and transmittance measurements. In these studies the envelops of the reflectance and transmittance spectra of thin films were used to calculate the optical constants^[4].</sup> For optical layers with large thicknesses, RI inhomogeneities can be readily determined from spectral data^[5].

LaF₃ is an important high-RI material used in deep ultraviolet (DUV) wavelength region. In the past the properties of LaF₃ films have been the focus of many research papers. Different deposition methods^[6] were employed to prepare LaF₃ films. The relation between the crystalline structure and the substrate temperature^[7], the micro-structure and laser-induced damage threshold (LIDT) characteristics of the LaF₃ films have been investigated. Several research papers also reported RI inhomogeneity of LaF₃ films. Liu *et al.*^[8] accused the RI inhomogeneous behavior to the loose structure of LaF₃ film.

Experimentally, RI inhomogeneity, which is important to coating design and manufacturing, is a function of various deposition parameters. In this letter, LaF₃ films are prepared by thermal evaporation at different substrate temperatures. Fused silica and CaF₂ are used as the substrates. Transmittance and reflectance spectra are measured with a Perkin Elmer Lambda 1050 spectrophotometer. An envelope method^[3,9–11] is applied to calculate the RI inhomogeneities of LaF₃ films deposited on fused silica with different substrate temperatures. RI inhomogeneities of ${\rm LaF}_3$ films on fused silica and ${\rm CaF}_2$ substrates are compared.

LaF₃ films were deposited by molybdenum boat evaporation. The base pressure of the coating machine chamber was pumped down to less than 2×10^{-4} Pa using a rotary pump and a cryo pump. The substrate temperatures ranged from 250 to 400 °C with a step of 50 °C. Deposition rate of thin film was 0.1 nm/s, controlled by a quartz oscillator controller. When the substrate temperature was 350 °C, fused silica and CaF_2 were both used as the substrates in one process. The optical thickness of all the films was set to six guarter waves at 193 nm. Before coating, the substrates were cleaned with a UV photo cleaner at two main working wavelengths, 185 and 254 nm, to remove hydrocarbon contamination. Spectra of the films were measured with a Lambda 1050 spectrophotometer whose short wavelength limit is 180 nm. Before the measurement, the film samples were cleaned with UV photo cleaner for 40 min.

Assume a weakly inhomogeneous film as shown in Fig. 1(a), where $n_{\rm in}$ is the RI of the film close to the substrate and $n_{\rm out}$ is that close to air. The average RI, defined by $n_{\rm av} = (n_{\rm in} + n_{\rm out})/2$, represents the RI of the film, and Δn , defined by $\Delta n = n_{\rm out} - n_{\rm in}$, represents the difference of RIs close to the substrate and close to air, respectively. A negative Δn indicates a negative RI inhomogeneity of the film.



Fig. 1. (Color online) (a) Schematic diagram of inhomogeneous RI model and (b) reflectance of a negatively inhomogeneous film $(n_{\rm out} < n_{\rm in})$. $R_{\rm min}$ is below $R_{\rm sub}$.

In Fig. 1(b), the reflectance (R) of a negatively inhomogeneous film was schematically shown. Assuming $n_{\rm out} < n_{\rm in}$ and $n_{\rm sub} < n_{\rm av}$, the minimum reflectance $(R_{\rm min})$ of the film is smaller than the reflectance of the substrate $(R_{\rm sub})$. Using a characteristic matrix^[4],

$$\mathbf{M} = \begin{bmatrix} \left(\frac{n_{\rm in}}{n_{\rm out}}\right)^{\frac{1}{2}} \cos \delta & \frac{\mathrm{i} \sin \delta}{(n_{\rm out} n_{\rm in})^{\frac{1}{2}}} \\ \mathrm{i} \left(\frac{n_{\rm in}}{n_{\rm out}}\right)^{\frac{1}{2}} \sin \delta & \left(\frac{n_{\rm in}}{n_{\rm out}}\right)^{\frac{1}{2}} \cos \delta \end{bmatrix}$$

where δ is the phase thickness, the spectrum of the negatively inhomogeneous film can be calculated. The RI inhomogeneity, $\Delta n/n_{\rm av}$, can be express by

$$\frac{\Delta n}{n_{\rm av}} = \frac{n_{\rm sub}^2 - n_0^2}{4n_0 n_{\rm sub}} \frac{\Delta R}{R_{\rm sub}},$$

where ΔR is the difference between $R_{\rm sub}$ and $R_{\rm min}$, and n_0 and $n_{\rm sub}$ are the RIs of the incident medium and the substrate, respectively. The RIs, $n_{\rm in}$ and $n_{\rm out}$, can be calculated by an envelope method from the spectrophotometric measurements at extreme wavelengths^[9].

 LaF_3 films deposited on fused silica substrates at different substrate temperatures showed a RI inhomogeneity, as shown in Fig. 2. All LaF₃ films showed a negative RI inhomogeneity. The RI decreased as the substrate temperature increased. Then the maximum of transmittance spectrum was higher than that of the substrate due to antireflection effect.

The RIs of the LaF3 thin films were calculated by the envelope method using the maxima and minima of R and T at quarter and half wavelengths. RIs, $n_{\rm out}$, and $n_{\rm in}$ of the films deposited at different substrate temperatures at 193 nm were summarized in Table 1.



Fig. 2. (Color online) (a) Transmittance and (b) reflectance spectra of the bare fused silica substrate and LaF₃ films prepared at 250, 300, 350, and 400 $^{\circ}$ C, respectively.

Table 1. RIs, n_{out} , n_{in} , and Inhomogeneity of LaF3Films Prepared at Different SubstrateTemperatures at 193 nm

Temperature (°C)	$n_{ m out}$	$n_{ m in}$	Δn	$\Delta n/n_{\rm av}$ (%)	<i>d</i> (nm)
250	1.5200	1.6888	0.1688	12.85	193.9
300	1.6066	1.7057	0.0991	5.98	171.2
350	1.6628	1.7215	0.0587	3.47	174.3
400	1.6906	1.7272	0.0366	2.14	170.1



Fig. 3. (Color online) Transmittance spectra of LaF_3 films prepared at 350 °C on (a) fused silica and (b) CaF_2 substrate.

From Table 1 we can see that both $n_{\rm out}$ and $n_{\rm in}$ increase as the substrate temperature increases, indicating the overall RI of the film increases with the increasing substrate temperature. At the same time Δn , the difference between $n_{\rm out}$ and $n_{\rm in}$, decreases with the increasing substrate temperature. Therefore, the RI inhomogeneity, $\Delta n/n_{\rm av}$, decreases as the substrate temperature increases. This is because as the substrate temperature increases, more thermal energy causes faster molecular movement, results in less voids in the film. Such a dense structure results in a high packing density, and consequently a decrease in the RI inhomogeneity behavior.

Figure 3 shows the transmittance spectra of LaF₃ films deposited on fused silica and CaF₂ substrates at substrate temperature of 350 °C. Clearly, LaF₃ film deposited on CaF₂ substrate presented negligible RI inhomogeneity, as compared to that deposited on fused silica substrate. This is due to the fact that fused silica has an amorphous structure, while CaF₂ has a cubic-crystalline structure. As LaF₃ material has the same crystalline structure as CaF₂, it could grow on CaF₂ substrate following homoepitaxy which had little dislocation in the film^[12]. In this case the film grows homogeneously.

In conclusion, RI inhomogeneities of LaF_3 films prepared by molybdenum boat evaporation at different substrate temperatures and on different substrates are investigated. The experimental results reveal that LaF_3 films deposited on fused silica substrates present strong negative inhomogeneity of RI, with the inhomogeneity decreased as the substrate temperature increasing. On the other hand, LaF_3 films deposited on CaF_2 substrates show negligible RI inhomogeneity.

References

- A. V. Tikhonravov, M. K. Trubetskov, B. T. Sullivan, and J. A. Dobrowolski, Appl. Opt. 36, 7188 (1997).
- J. A. Dobrowolski and P. G. Verly, Proc. SPIE 2046, (1993).
- D. P. Arndt, R. M. A. Azzam, J. M. Bennett, J. P. Borgogno, C. K. Carniglia, W. E. Case, J. A. Dobrowolski, U. J. Gibson, T. T. Hart, F. C. Ho, V. A. Hodgkin, W. P. Klapp, H. A. Macleod, E. Pelletier, M. K. Purvis, D. M. Quinn, D. H. Strome, R. Swenson, P. A. Temple, and T. F. Thonn, Appl. Opt. 23, 3571 (1984).
- B. Bovard, F. J. Van Milligen, M. J. Messerly, S. G. Saxe, and H. A. Macleod, Appl. Opt. **12**, 1803 (1985).
- J. P. Borgogno, F. Flory, P. Roche, B. Schmitt, G. Albrand, E. Pelletier, and H. A. Macleod, Appl. Opt. 23, 3567 (1984).

- 6. Y. Taki, Vacuum 74, 431 (2004).
- M. Vijayakumar, S. Selvasekarapandian, T. Gnanasekarah, S. Fujihara, and S. Koji, J. Fluorine Chem. 125, 1119 (2004).
- M. C. Liu, C. C. Lee, M. Kaneko, K. Nakahira, and Y. Takano, Opt. Eng. 45, 083801 (2006).
- J. H. Lee and C. K. Hwangbo, Surf. Coating. Tech. 128, 280 (2000).
- 10. S. Humphrey, Appl. Opt. **21**, 4660 (2007).
- 11. N. K. Sahoo and A. P. Shapiro, Appl. Opt. 4, 698 (1998).
- 12. Z. Wu and B. Wu, *The Growth of Thin Film* (in Chinese) (Science Press, Beijing, 2001) pp. 181-187.